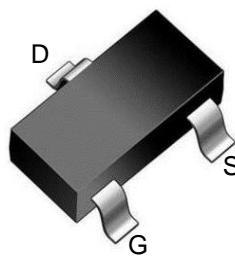
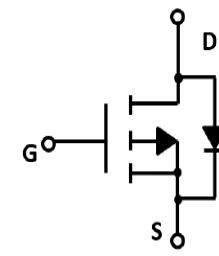


■ Features

- $V_{DS} (V) = 250V$
- $I_D = 400 \text{ mA}$
- $R_{DS(on)} < 3.4 \Omega (V_{GS} = 10V)$
- $R_{DS(on)} < 4.5 \Omega (V_{GS} = 4.5V)$



SOT-23 top view



Schematic diagram

 ■ Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	250	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	0.1	A
Pulsed Drain Current (Note 1)	I_{DM}	1.0	
Power Dissipation	P_D	1.5	W
Thermal Resistance Junction- to-Ambient (Note 2)	R_{thJA}	100	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to 150	

 ■ Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DBS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	100			V
Zero Gate Voltage Drain Current	$I_{DS(0)}$	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
Gate Threshold Voltage (Note 3)	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	2		V
Static Drain-Source On-Resistance (Note 3)	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=3\text{A}$		3.4		Ω
		$V_{GS}=4.5\text{V}, I_D=3\text{A}$		4.5		
Forward Transconductance (Note 3)	g_{FS}	$V_{DS}=5\text{V}, I_D=3\text{A}$	5			S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=50\text{V}, f=1\text{MHz}$ (Note 4)	650			pF
Output Capacitance	C_{oss}		24			
Reverse Transfer Capacitance	C_{rss}		20			
Total Gate Charge	Q_g	$V_{GS}=10\text{V}, V_{DS}=50\text{V}, I_D=3\text{A}$ (Note 4)	20			nC
Gate Source Charge	Q_{gs}		2.1			
Gate Drain Charge	Q_{gd}		3.3			
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10\text{V}, V_{DD}=50\text{V}, R_L=19\Omega, R_G=3\Omega$ (Note 4)	6			ns
Turn-On Rise Time	t_r		4			
Turn-Off Delay Time	$t_{d(off)}$		20			
	f		4			
Body-Diode Forward Current (Note 2)	I_S				3	A
Diode Forward Voltage (Note 3)	V_{SD}	$I_S=3\text{A}, V_{GS}=0\text{V}$			1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10 \text{ sec}$.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production.

■ Typical Characteristics and Thermal Characteristics (Curves)

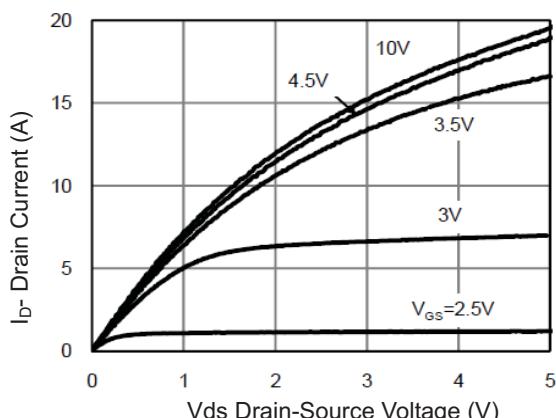


Figure 1 Output Characteristics

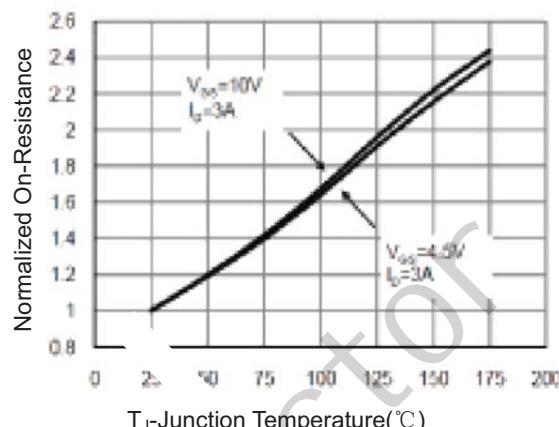


Figure 4 Rdson-JunctionTemperature

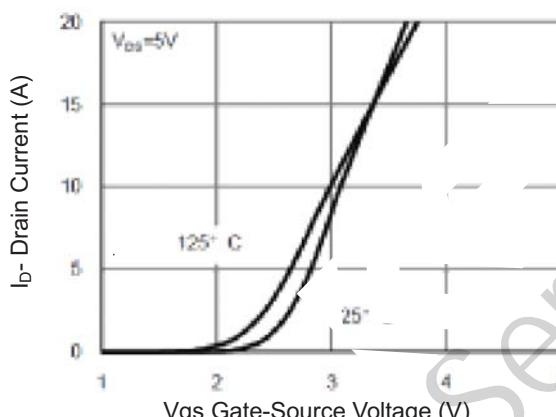


Figure 2 Transfer Characteristics

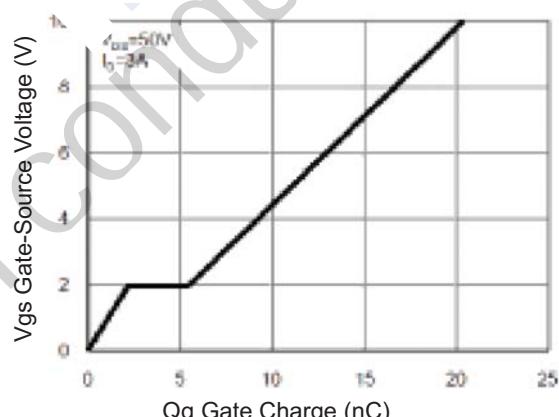


Figure 5 Gate Charge

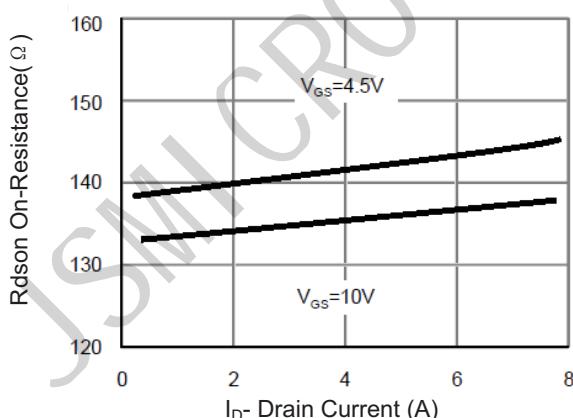


Figure 3 Rdson- Drain Current

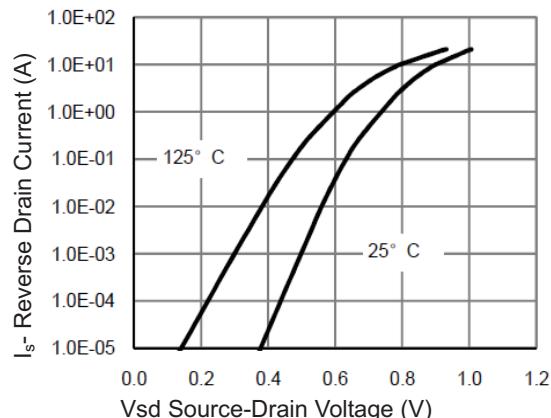
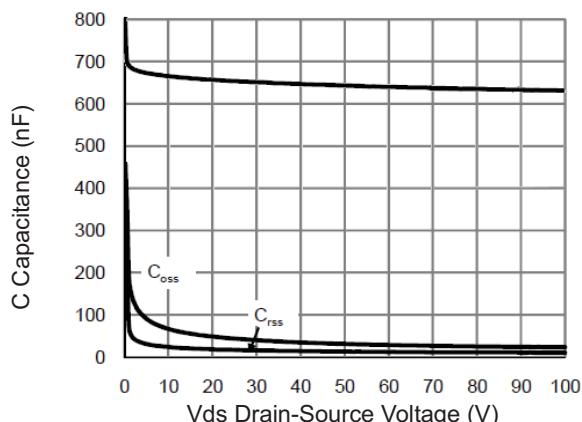
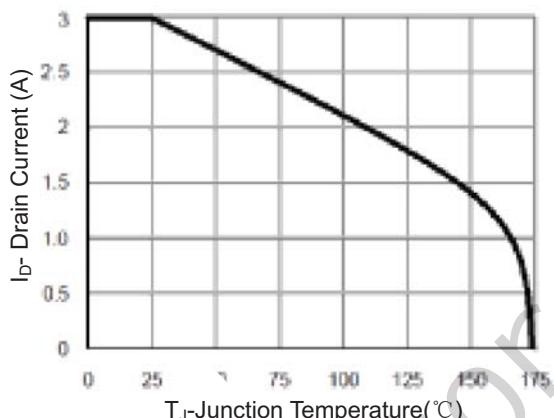
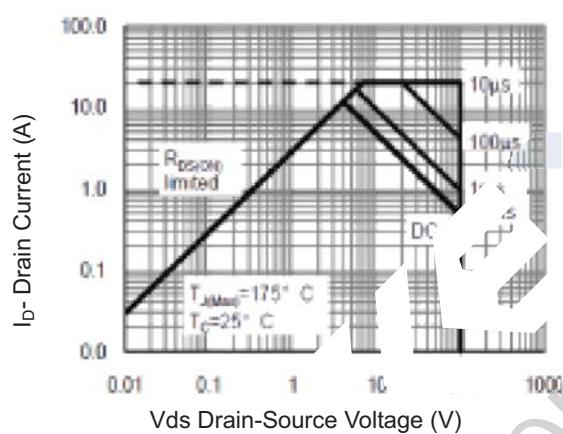
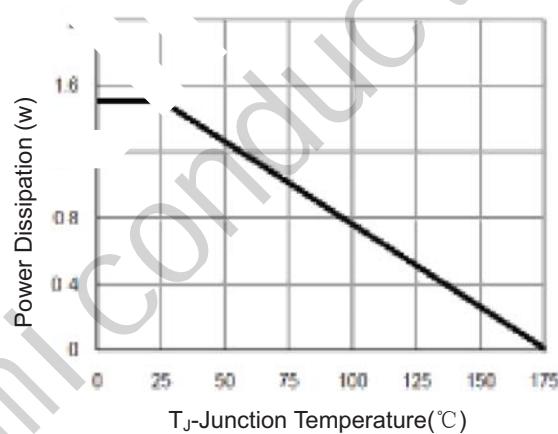
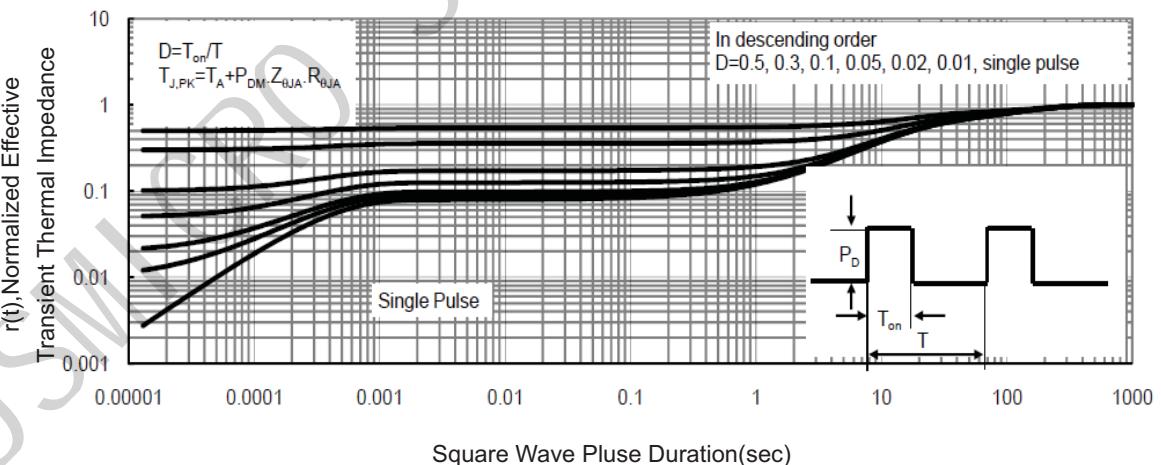


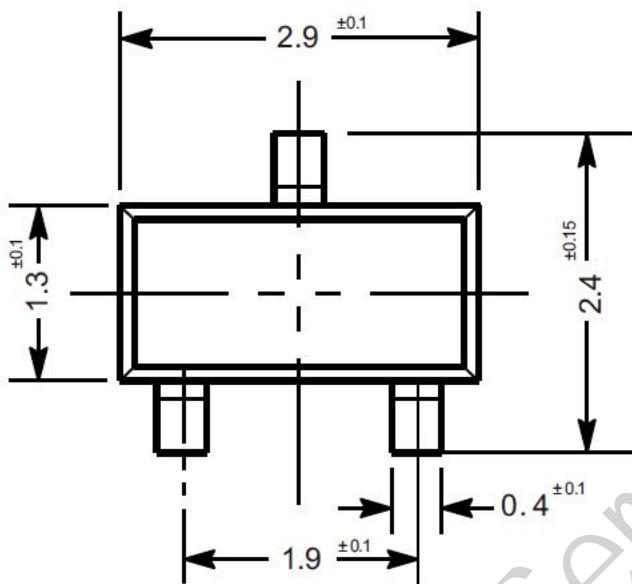
Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 BV_{DSS} vs Junction Temperature

Figure 8 Safe Operation Area

Figure 10 Power De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance

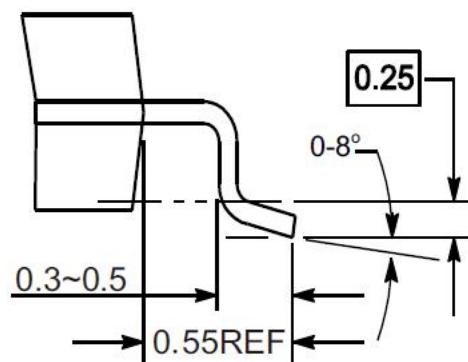
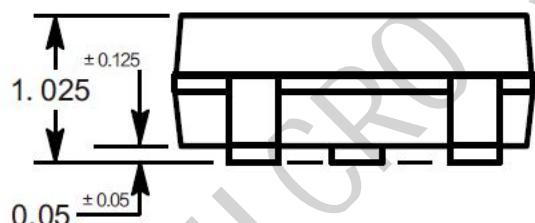
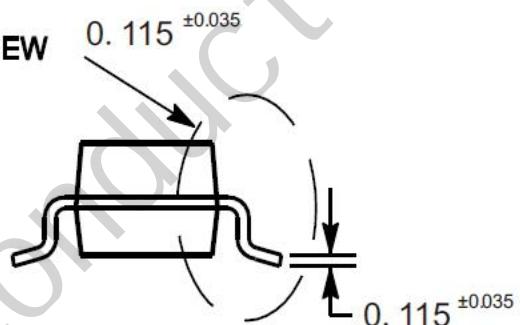
Package Outline

SOT-23

Dimensions in mm



SEE VIEW



VIEW C